SP168GN

(UL ANSI: NO ANSI) No-flow, Dust Free

FEATURES

- Excellent mechanical process ability, punching process applicable.
- Minimal resin flow, flexible and nearly powderless contamination.
- Hi-Tg and halogen free.

APPLICATIONS

Suitable for bonding use in heat sink board, die cavity board and multilayer rigid-flex PCB applications.

GENERAL PROPERTIES

Test Items	Test Method	Test Condition	Unit	Typical Value
Tg	IPC-TM-650 2.4.25	DSC	℃	165
	IPC-TM-650 2.4.24.2	DMA		180
Peel Strength	IPC-TM-650 2.4.8	Copper Foil (1/2 oz)	N/mm	1.2
	IPC-TM-650 2.4.8	Copper Foil (1 oz)		1.5
	IPC-TM-650 2.4.9	CVL		1.1
T288(unclad)	IPC-TM-650 2.4.24.1	TMA	min	>30
Td(5%W.loss)	IPC-TM-650 2.4.24.6	TGA	℃	380
Dipping test	-	288℃,solder dip	s	>600
Water Absorption	IPC-TM-650 2.6.2.1	E-1/105+D-24/23	%	0.14
CTE, Z-axis	IPC-TM-650 2.4.24	Before Tg/TMA	PPM/℃	70
	IPC-TM-650 2.4.24	After Tg/TMA		300
Dielectric Constant (RC 63%@1GHz)	IPC-TM-650 2.5.5.9	C-24/23/50	-	3.95
Dissipation Factor (RC 63%@1GHz)	IPC-TM-650 2.5.5.9	C-24/23/50	-	0.017
Flammability	UL94	C-48/23/50	Rating	V-0
		E-24/125		

Remarks: Specimen thickness: 0.8mm. All the typical value listed above is for your reference only, please turn to Shengyi Technology Co., Ltd. for detailed information.

Explanations: C=Humidity conditioning; D=Immersion conditioning in distilled water; E=Temperature conditioning.

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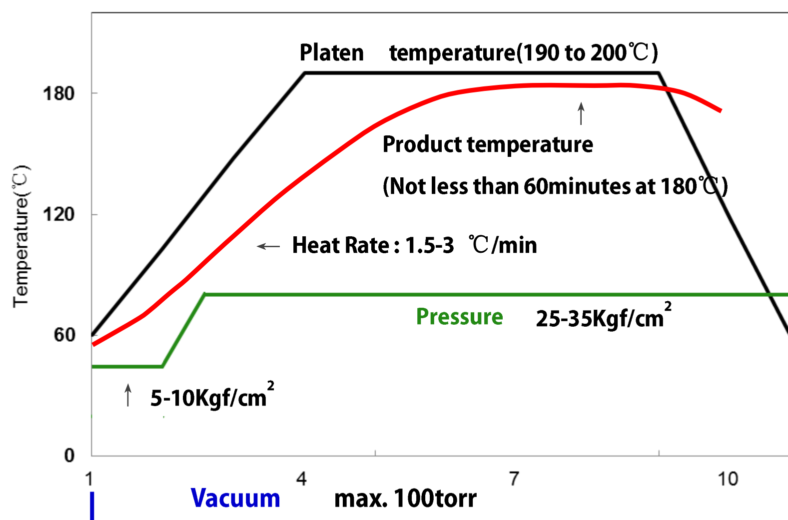
PURCHASING INFORMATION

Specification	Resin Content (%)	Resin Flow (mm)	Cured thickness(μm)
1078	70	≤0.5	100
	67	≤0.5	90
	63	≤0.5	80
	60	≤0.5	70
1067	68	≤0.5	60
	63	≤0.5	50
1037	68	≤0.5	45
	63	≤0.5	40
1027	60	≤0.5	30
	53	≤0.5	25

Remarks: Available in roll size or panel form.

HOT PRESSING CYCLE



Heat Rate: 1.5-3.0℃/min (70-130℃)

Kiss Pressure：5-10kgf/cm²

Full Pressure：25-35kgf/cm²

Apply Full Pressure: 70-110 ℃/min

Cure Temperature：≥180℃

Cure Time：≥60min